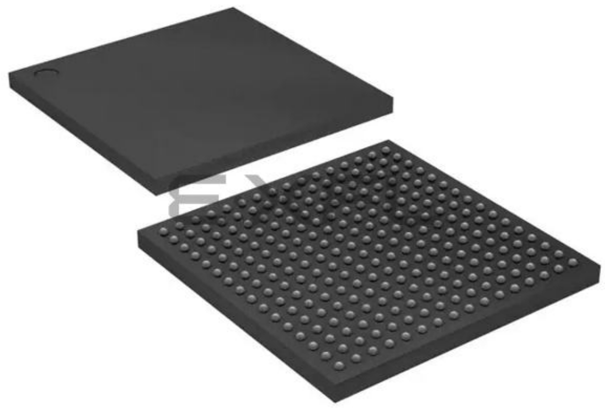
Intel - EP4CE22F17C7N Datasheet



Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	1395
Number of Logic Elements/Cells	22320
Total RAM Bits	608256
Number of I/O	153
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-LBGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce22f17c7n

- Cyclone IV GX devices offer up to eight high-speed transceivers that provide:
  - Data rates up to 3.125 Gbps
  - 8B/10B encoder/decoder
  - 8-bit or 10-bit physical media attachment (PMA) to physical coding sublayer (PCS) interface
  - Byte serializer/deserializer (SERDES)
  - Word aligner
  - Rate matching FIFO
  - TX bit slipper for Common Public Radio Interface (CPRI)
  - Electrical idle
  - Dynamic channel reconfiguration allowing you to change data rates and protocols on-the-fly
  - Static equalization and pre-emphasis for superior signal integrity
  - 150 mW per channel power consumption
  - Flexible clocking structure to support multiple protocols in a single transceiver block
- Cyclone IV GX devices offer dedicated hard IP for PCI Express (PIPE) (PCIe) Gen 1:
  - ×1, ×2, and ×4 lane configurations
  - End-point and root-port configurations
  - Up to 256-byte payload
  - One virtual channel
  - 2 KB retry buffer
  - 4 KB receiver (Rx) buffer
- Cyclone IV GX devices offer a wide range of protocol support:
  - PCIe (PIPE) Gen 1 ×1, ×2, and ×4 (2.5 Gbps)
  - Gigabit Ethernet (1.25 Gbps)
  - CPRI (up to 3.072 Gbps)
  - XAUI (3.125 Gbps)
  - Triple rate serial digital interface (SDI) (up to 2.97 Gbps)
  - Serial RapidIO (3.125 Gbps)
  - Basic mode (up to 3.125 Gbps)
  - V-by-One (up to 3.0 Gbps)
  - DisplayPort (2.7 Gbps)
  - Serial Advanced Technology Attachment (SATA) (up to 3.0 Gbps)
  - OBSAI (up to 3.072 Gbps)

Cyclone IV Device Family Speed Grades

Table 1–5 lists the Cyclone IV GX devices speed grades.

Table 1–5. Speed Grades for the Cyclone IV GX Device Family

Device	F169	F324	F484	F672	F896
EP4CGX15	C6, C7, C8, I7	—	—	—	—
EP4CGX22	C6, C7, C8, I7	C6, C7, C8, I7	—	—	—
EP4CGX30	C6, C7, C8, I7	C6, C7, C8, I7	C6, C7, C8, I7	—	—
EP4CGX50	—	—	C6, C7, C8, I7	C6, C7, C8, I7	—
EP4CGX75	—	—	C6, C7, C8, I7	C6, C7, C8, I7	—
EP4CGX110	—	—	C7, C8, I7	C7, C8, I7	C7, C8, I7
EP4CGX150	—	—	C7, C8, I7	C7, C8, I7	C7, C8, I7

Table 1–6 lists the Cyclone IV E devices speed grades.

Table 1–6. Speed Grades for the Cyclone IV E Device Family *(1), (2)*

Device	E144	M164	M256	U256	F256	F324	U484	F484	F780
EP4CE6	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	I7N	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	—	—
EP4CE10	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	I7N	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	—	—
EP4CE15	C8L, C9L, I8L C6, C7, C8, I7	I7N	C7N, I7N	I7N	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	C8L, C9L, I8L C6, C7, C8, I7, A7	—
EP4CE22	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	I7N	C8L, C9L, I8L C6, C7, C8, I7, A7	—	—	—	—
EP4CE30	—	—	—	—	—	A7N	—	C8L, C9L, I8L C6, C7, C8, I7, A7	C8L, C9L, I8L C6, C7, C8, I7
EP4CE40	—	—	—	—	—	A7N	I7N	C8L, C9L, I8L C6, C7, C8, I7, A7	C8L, C9L, I8L C6, C7, C8, I7
EP4CE55	—	—	—	—	—	—	I7N	C8L, C9L, I8L C6, C7, C8, I7	C8L, C9L, I8L C6, C7, C8, I7
EP4CE75	—	—	—	—	—	—	I7N	C8L, C9L, I8L C6, C7, C8, I7	C8L, C9L, I8L C6, C7, C8, I7
EP4CE115	—	—	—	—	—	—	—	C8L, C9L, I8L C7, C8, I7	C8L, C9L, I8L C7, C8, I7

Notes to Table 1–6:

(1) C8L, C9L, and I8L speed grades are applicable for the 1.0-V core voltage.

(2) C6, C7, C8, I7, and A7 speed grades are applicable for the 1.2-V core voltage.

Figure 3–3 and Figure 3–4 show the address clock enable waveform during read and write cycles, respectively.

Figure 3–3. Cyclone IV Devices Address Clock Enable During Read Cycle Waveform

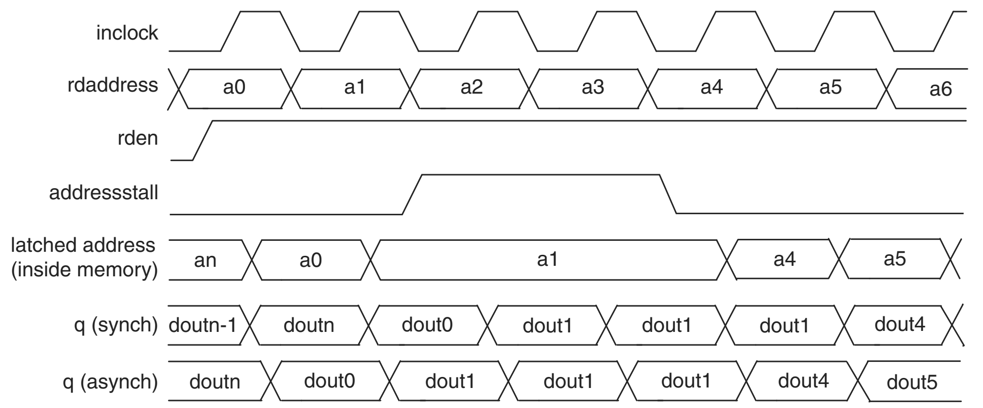
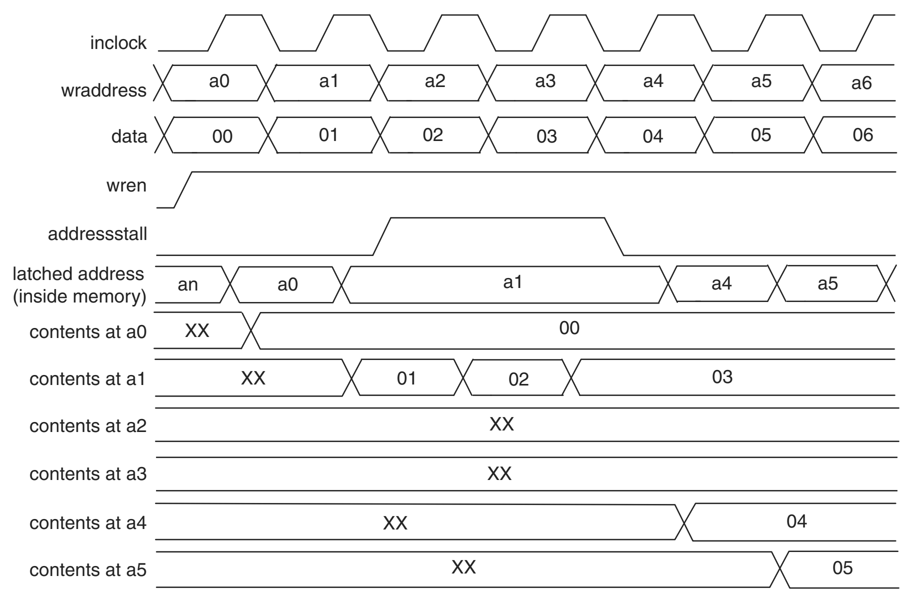


Figure 3–4. Cyclone IV Devices Address Clock Enable During Write Cycle Waveform

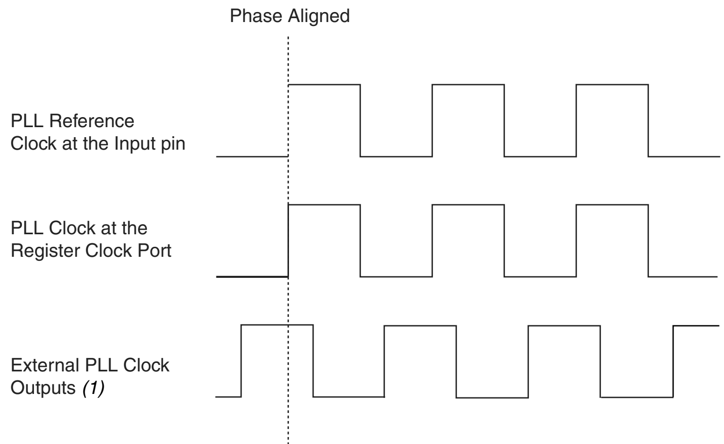


Mixed-Width Support

M9K memory blocks support mixed data widths. When using simple dual-port, true dual-port, or FIFO modes, mixed width support allows you to read and write different data widths to an M9K memory block. For more information about the different widths supported per memory mode, refer to “Memory Modes” on page 3–7.

Figure 5–14 shows a waveform example of the phase relationship of the PLL clocks in this mode.

Figure 5–14. Phase Relationship Between PLL Clocks in Normal Mode



Note to Figure 5–14:

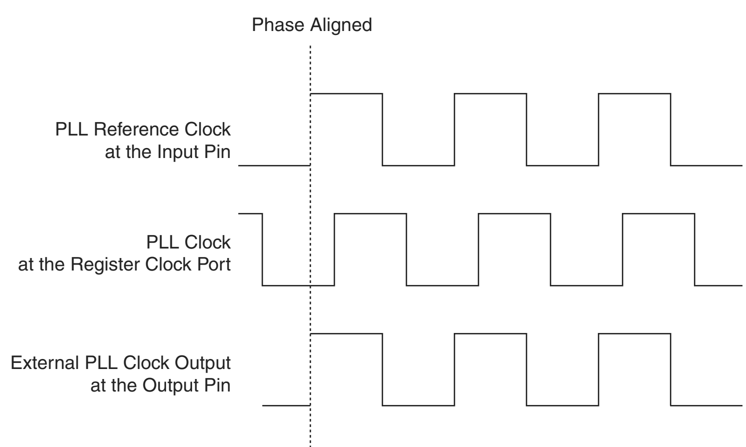
(1) The external clock output can lead or lag the PLL internal clock signals.

Zero Delay Buffer Mode

In zero delay buffer (ZDB) mode, the external clock output pin is phase-aligned with the clock input pin for zero delay through the device. When using this mode, use the same I/O standard on the input clock and output clocks to guarantee clock alignment at the input and output pins.

Figure 5–15 shows an example waveform of the phase relationship of the PLL clocks in ZDB mode.

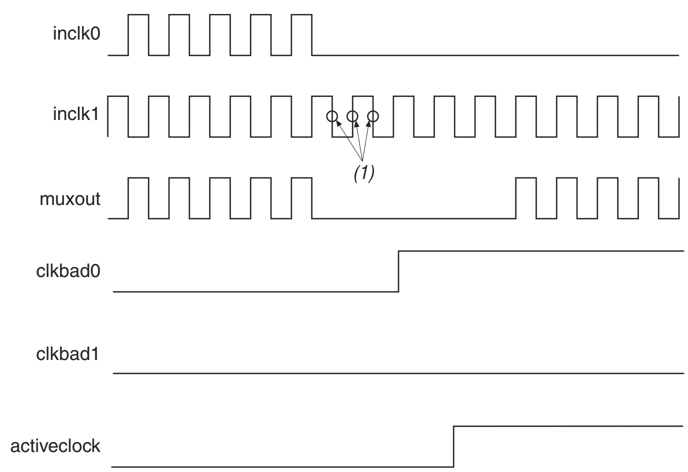
Figure 5–15. Phase Relationship Between PLL Clocks in ZDB Mode



20%. This feature is useful when clock sources can originate from multiple cards on the backplane, requiring a system-controlled switchover between frequencies of operation. Choose the secondary clock frequency so the VCO operates in the recommended frequency range. Also, set the M, N, and C counters accordingly to keep the VCO operating frequency in the recommended range.

Figure 5–18 shows a waveform example of the switchover feature when using automatic loss of clock detection. Here, the `inclk0` signal remains low. After the `inclk0` signal remains low for approximately two clock cycles, the clock-sense circuitry drives the `clkbad0` signal high. Also, because the reference clock signal is not toggling, the switchover state machine controls the multiplexer through the `clksw` signal to switch to `inclk1`.

Figure 5–18. Automatic Switchover Upon Clock Loss Detection *(1)*



Note to Figure 5–18:

(1) Switchover is enabled on the falling edge of `inclk0` or `inclk1`, depending on which clock is available. In this figure, switchover is enabled on the falling edge of `inclk1`.

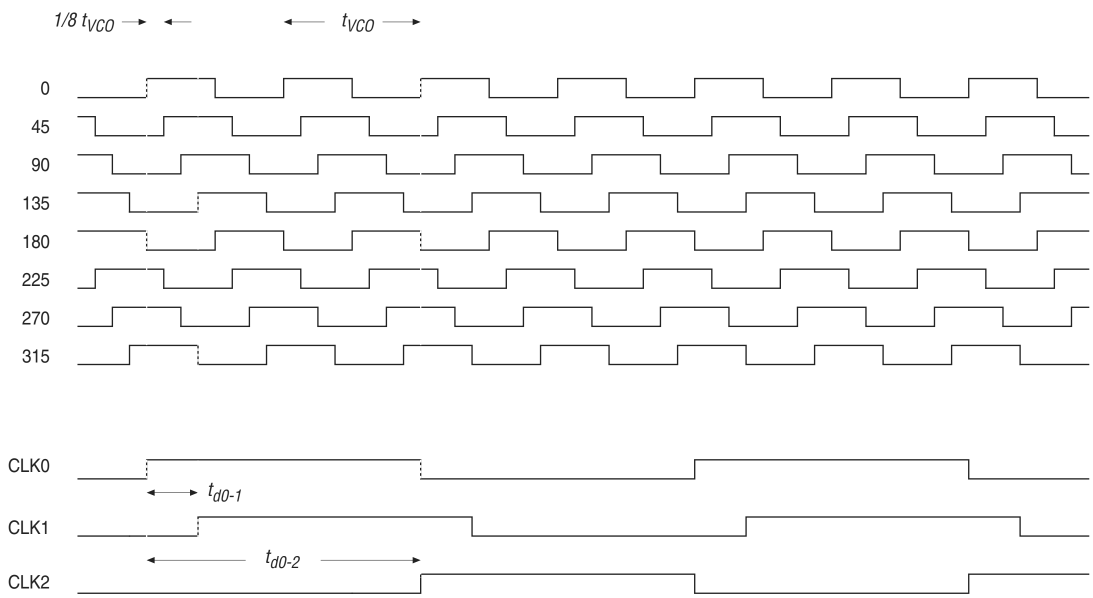
Manual Override

If you are using the automatic switchover, you must switch input clocks with the manual override feature with the `clkswitch` input.

Figure 5–19 shows an example of a waveform illustrating the switchover feature when controlled by `clkswitch`. In this case, both clock sources are functional and `inclk0` is selected as the reference clock. A low-to-high transition of the `clkswitch` signal starts the switchover sequence. The `clkswitch` signal must be high for at least three clock cycles (at least three of the longer clock period if `inclk0` and `inclk1` have different frequencies). On the falling edge of `inclk0`, the reference clock of the counter, `muxout`, is gated off to prevent any clock glitching. On the falling edge of `inclk1`, the reference clock multiplexer switches from `inclk0` to `inclk1` as the PLL reference, and the `activeclock` signal changes to indicate which clock is currently feeding the PLL.

Figure 5–21 shows an example of phase shift insertion using fine resolution through VCO phase taps method. The eight phases from the VCO are shown and labeled for reference. In this example, `CLK0` is based on 0° phase from the VCO and has the C value for the counter set to one. The `CLK1` signal is divided by four, two VCO clocks for high time and two VCO clocks for low time. `CLK1` is based on the 135° phase tap from the VCO and has the C value for the counter set to one. The `CLK1` signal is also divided by four. In this case, the two clocks are offset by 3 Φ_{fine}. `CLK2` is based on the 0° phase from the VCO but has the *C* value for the counter set to three. This creates a delay of two Φ_{coarse} (two complete VCO periods).

Figure 5–21. Delay Insertion Using VCO Phase Output and Counter Delay Time



You can use the coarse and fine phase shifts to implement clock delays in Cyclone IV devices.

Cyclone IV devices support dynamic phase shifting of VCO phase taps only. The phase shift is configurable for any number of times. Each phase shift takes about one `scanclk` cycle, allowing you to implement large phase shifts quickly.

PLL Cascading

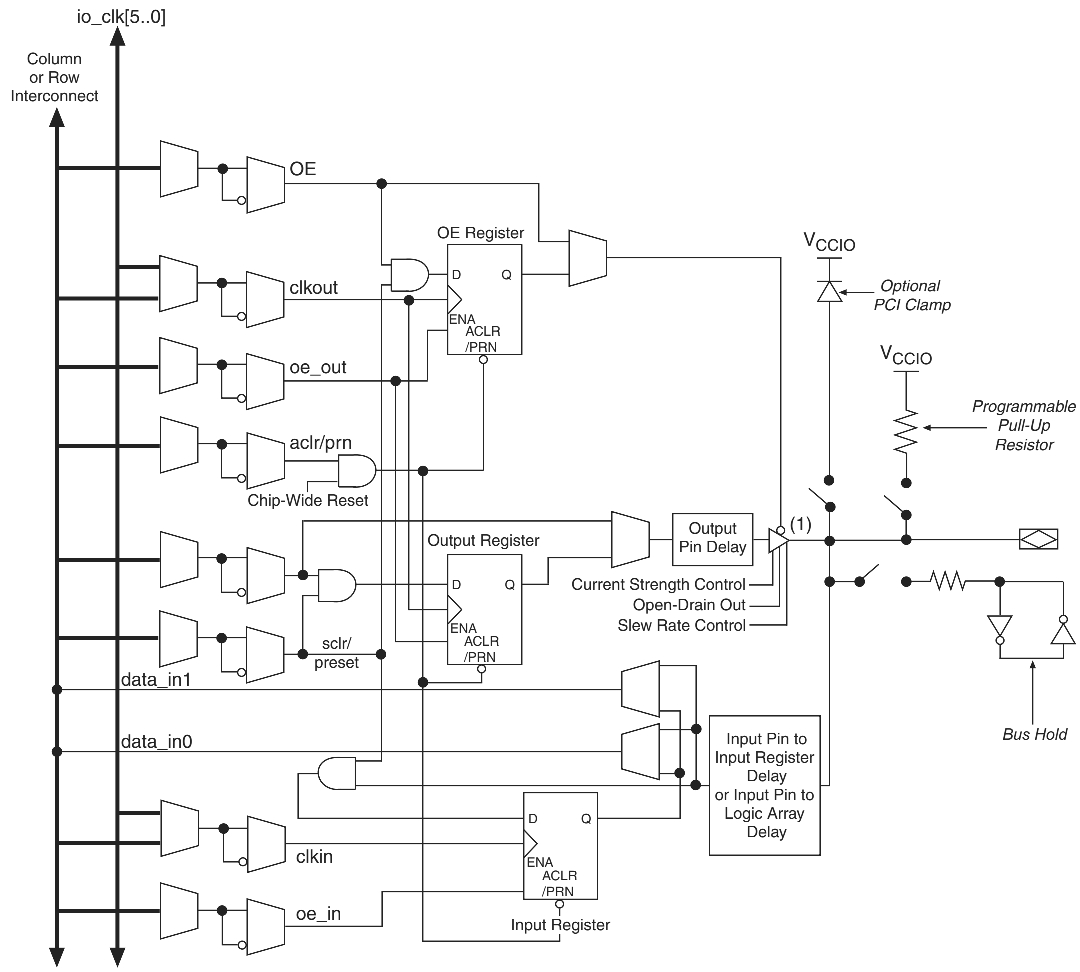
Cyclone IV devices allow cascading between general purpose PLLs and multipurpose PLLs in normal or direct mode through the GCLK network. If your design cascades PLLs, the source (upstream) PLL must have a low-bandwidth setting, while the destination (downstream) PLL must have a high-bandwidth setting.

☞ `PLL_6` and `PLL7` have upstream cascading capability only.

☞ PLL cascading is not supported when used in transceiver applications.

Figure 6–1 shows the Cyclone IV devices IOE structure for single data rate (SDR) operation.

Figure 6–1. Cyclone IV IOEs in a Bidirectional I/O Configuration for SDR Mode



Note to Figure 6–1:

(1) Tri-state control is not available for outputs configured with true differential I/O standards.

I/O Element Features

The Cyclone IV IOE offers a range of programmable features for an I/O pin. These features increase the flexibility of I/O utilization and provide a way to reduce the usage of external discrete components, such as pull-up resistors and diodes.

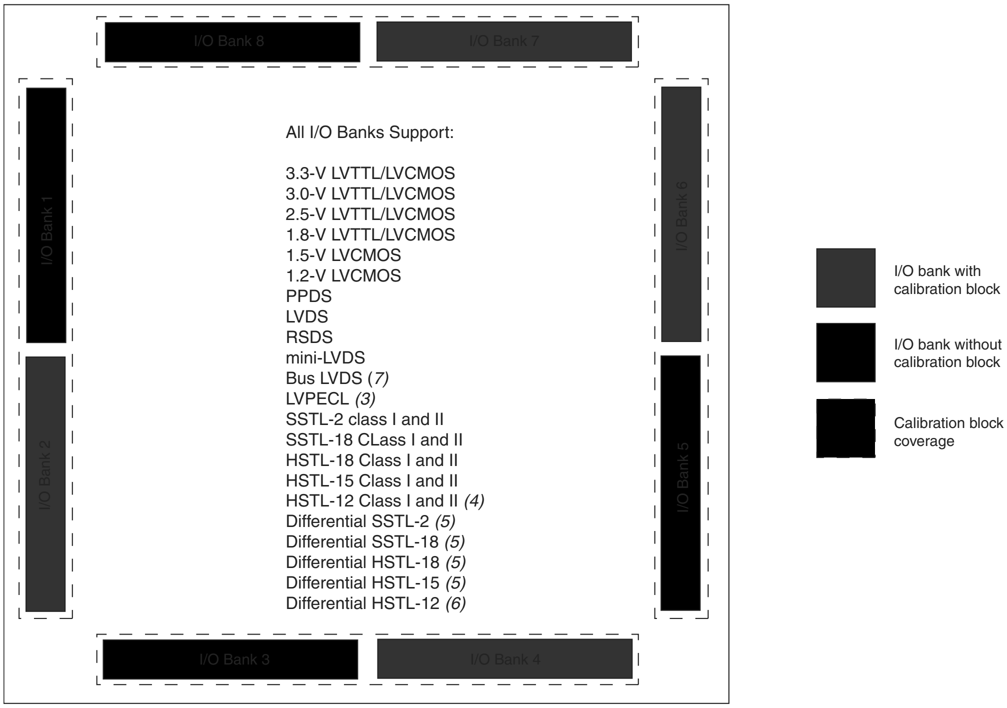
Programmable Current Strength

The output buffer for each Cyclone IV I/O pin has a programmable current strength control for certain I/O standards.

The LVTTL, LVCMOS, SSTL-2 Class I and II, SSTL-18 Class I and II, HSTL-18 Class I and II, HSTL-15 Class I and II, and HSTL-12 Class I and II I/O standards have several levels of current strength that you can control.

Figure 6–9 shows the overview of Cyclone IV E I/O banks.

Figure 6–9. Cyclone IV E I/O Banks *(1)*, *(2)*



Notes to Figure 6–9:

(1) This is a top view of the silicon die. This is only a graphical representation. For exact pin locations, refer to the pin list and the Quartus II software.

(2) True differential (PPDS, LVDS, mini-LVDS, and RSDS I/O standards) outputs are supported in row I/O banks 1, 2, 5, and 6 only. External resistors are needed for the differential outputs in column I/O banks.

(3) The LVPECL I/O standard is only supported on clock input pins. This I/O standard is not supported on output pins.

(4) The HSTL-12 Class II is supported in column I/O banks 3, 4, 7, and 8 only.

(5) The differential SSTL-18 and SSTL-2, differential HSTL-18, and HSTL-15 I/O standards are supported only on clock input pins and phase-locked loops (PLLs) output clock pins. Differential SSTL-18, differential HSTL-18, and HSTL-15 I/O standards do not support Class II output.

(6) The differential HSTL-12 I/O standard is only supported on clock input pins and PLL output clock pins. Differential HSTL-12 Class II is supported only in column I/O banks 3, 4, 7, and 8.

(7) BLVDS output uses two single-ended outputs with the second output programmed as inverted. BLVDS input uses true LVDS input buffer.

Each Cyclone IV I/O bank has a VREF bus to accommodate voltage-referenced I/O standards. Each `VREF` pin is the reference source for its V_{REF} group. If you use a V_{REF} group for voltage-referenced I/O standards, connect the `VREF` pin for that group to the appropriate voltage level. If you do not use all the V_{REF} groups in the I/O bank for voltage-referenced I/O standards, you can use the `VREF` pin in the unused voltage-referenced groups as regular I/O pins. For example, if you have SSTL-2 Class I input pins in I/O bank 1 and they are all placed in the `VREFB1N[0]` group, `VREFB1N[0]` must be powered with 1.25 V, and the remaining `VREFB1N[1..3]` pins (if available) are used as I/O pins. If multiple V_{REF} groups are used in the same I/O bank, the `VREF` pins must all be powered by the same voltage level because the `VREF` pins are shorted together within the same I/O bank.

When `VREF` pins are used as regular I/Os, they have higher pin capacitance than regular user I/O pins. This has an impact on the timing if the pins are used as inputs and outputs.

For more information about `VREF` pin capacitance, refer to the pin capacitance section in the *Cyclone IV Device Datasheet* chapter.

For information about how to identify V_{REF} groups, refer to the Cyclone IV **Device Pin-Out** files or the **Quartus II Pin Planner** tool.

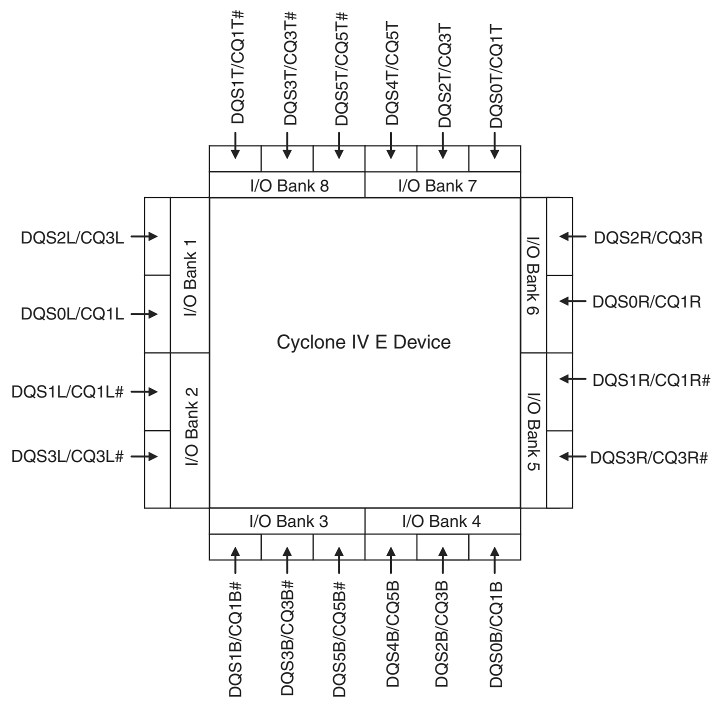
Table 6–4 and Table 6–5 summarize the number of `VREF` pins in each I/O bank for the Cyclone IV device family.

Table 6–4. Number of VREF Pins Per I/O Bank for Cyclone IV E Devices (Part 1 of 2)

Device	EP4CE6			EP4CE10			EP4CE15						EP4CE22			EP4CE30			EP4CE40				EP4CE55			EP4CE75			EP4CE115	
I/O Bank *(1)*	144-EQPF	256-UBGA	256-FBGA	144-EQPF	256-UBGA	256-FBGA	144-EQPF	164-MBGA	256-MBGA	256-UBGA	256-FBGA	484-FBGA	144-EQPF	256-UBGA	256-FBGA	324-FBGA	484-FBGA	780-FBGA	324-FBGA	484-UBGA	484-FBGA	780-FBGA	484-UBGA	484-FBGA	780-FBGA	484-UBGA	484-FBGA	780-FBGA	484-FBGA	780-FBGA
1	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
2	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
3	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
4	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
5	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
6	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
7	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3

Figure 7–5 shows the location and numbering of the DQS, DQ, or CQ# pins in the Cyclone IV E device I/O banks.

Figure 7–5. DQS, CQ, or CQ# Pins in Cyclone IV E I/O Banks *(1)*



Note to Figure 7–5:

(1) The DQS, CQ, or CQ# pin locations in this diagram apply to all packages in Cyclone IV E devices except devices in 144-pin EQFP.

During device configuration, Cyclone IV E devices read configuration data using the parallel interface and configure their SRAM cells. This scheme is referred to as the AP configuration scheme because the device controls the configuration interface. This scheme contrasts with the FPP configuration scheme, where an external host controls the interface.

AP Configuration Supported Flash Memories

The AP configuration controller in Cyclone IV E devices is designed to interface with two industry-standard flash families—the Micron P30 Parallel NOR flash family and the Micron P33 Parallel NOR flash family. Unlike serial configuration devices, both of the flash families supported in AP configuration scheme are designed to interface with microprocessors. By configuring from an industry standard microprocessor flash which allows access to the flash after entering user mode, the AP configuration scheme allows you to combine configuration data and user data (microprocessor boot code) on the same flash memory.

The Micron P30 flash family and the P33 flash family support a continuous synchronous burst read mode at 40 MHz `DCLK` frequency for reading data from the flash. Additionally, the Micron P30 and P33 flash families have identical pin-out and adopt similar protocols for data access.

☞ Cyclone IV E devices use a 40-MHz oscillator for the AP configuration scheme. The oscillator is the same oscillator used in the Cyclone IV E AS configuration scheme.

Table 8–10 lists the supported families of the commodity parallel flash for the AP configuration scheme.

Table 8–10. Supported Commodity Flash for AP Configuration Scheme for Cyclone IV E Devices *(1)*

Flash Memory Density	Micron P30 Flash Family *(2)*	Micron P33 Flash Family *(3)*
64 Mbit	✓	✓
128 Mbit	✓	✓
256 Mbit	✓	✓

Notes to Table 8–10:

(1) The AP configuration scheme only supports flash memory speed grades of 40 MHz and above.

(2) 3.3- , 3.0-, 2.5-, and 1.8-V I/O options are supported for the Micron P30 flash family.

(3) 3.3-, 3.0- and 2.5-V I/O options are supported for the Micron P33 flash family.

Configuring Cyclone IV E devices from the Micron P30 and P33 family 512-Mbit flash memory is possible, but you must properly drive the extra address and `FLASH_nCE` pins as required by these flash memories.

To check for supported speed grades and package options, refer to the respective flash datasheets.

The AP configuration scheme in Cyclone IV E devices supports flash speed grades of 40 MHz and above. However, AP configuration for all these speed grades must be capped at 40 MHz. The advantage of faster speed grades is realized when your design in the Cyclone IV E devices accesses flash memory in user mode.

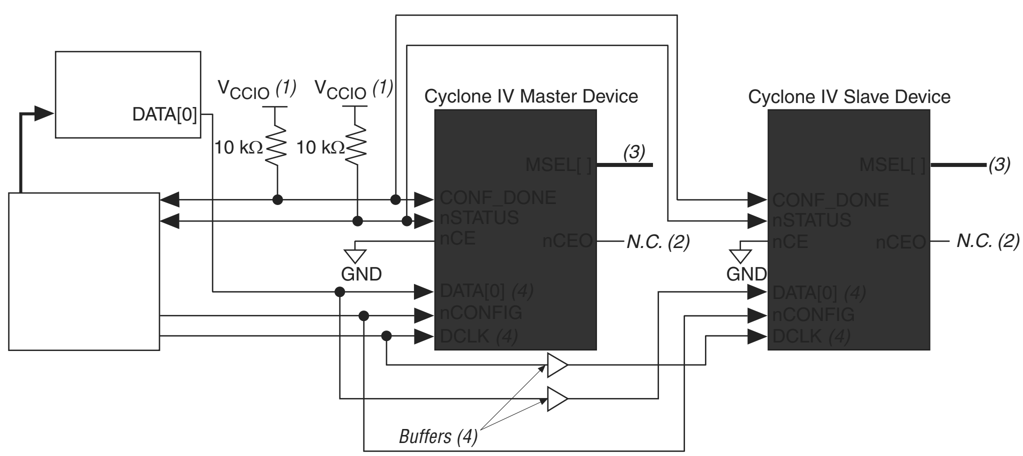
After the first device completes configuration in a multi-device configuration chain, its `nCEO` pin drives low to activate the `nCE` pin of the second device, which prompts the second device to begin configuration. The second device in the chain begins configuration in one clock cycle. Therefore, the transfer of data destinations is transparent to the external host device. `nCONFIG`, `nSTATUS`, `DCLK`, `DATA[0]`, and `CONF_DONE` configuration pins are connected to every device in the chain. To ensure signal integrity and prevent clock skew problems, configuration signals may require buffering. Ensure that `DCLK` and `DATA` lines are buffered. All devices initialize and enter user mode at the same time because all `CONF_DONE` pins are tied together.

If any device detects an error, configuration stops for the entire chain and you must reconfigure the entire chain because all `nSTATUS` and `CONF_DONE` pins are tied together. For example, if the first device flags an error on `nSTATUS`, it resets the chain by pulling its `nSTATUS` pin low. This behavior is similar to a single device detecting an error.

You can have multiple devices that contain the same configuration data in your system. To support this configuration scheme, all device `nCE` inputs are tied to GND, while the `nCEO` pins are left floating. `nCONFIG`, `nSTATUS`, `DCLK`, `DATA[0]`, and `CONF_DONE` configuration pins are connected to every device in the chain. To ensure signal integrity and prevent clock skew problems, configuration signals may require buffering. Ensure that the `DCLK` and `DATA` lines are buffered. Devices must be of the same density and package. All devices start and complete configuration at the same time.

Figure 8–15 shows a multi-device PS configuration when both Cyclone IV devices are receiving the same configuration data.

Figure 8–15. Multi-Device PS Configuration When Both Devices Receive the Same Data



Notes to Figure 8–15:

(1) You must connect the pull-up resistor to a supply that provides an acceptable input signal for all devices in the chain. V_{CC} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host.

(2) The `nCEO` pins of both devices are left unconnected or used as user I/O pins when configuring the same configuration data into multiple devices.

(3) The `MSEL` pin settings vary for different configuration voltage standards and POR time. To connect the `MSEL` pins, refer to Table 8–3 on page 8–8, Table 8–4 on page 8–8, and Table 8–5 on page 8–9. Connect the `MSEL` pins directly to V_{CCA} or GND.

(4) All I/O inputs must maintain a maximum AC voltage of 4.1 V. `DATA[0]` and `DCLK` must fit the maximum overshoot outlined in Equation 8–1 on page 8–5.

- External configuration reset (`nCONFIG`) assertion
- User watchdog timer time out

Table 8–24 lists the contents of the current state logic in the status register, when the remote system upgrade master state machine is in factory configuration or application configuration accessing the factory information or application information, respectively. The status register bit in Table 8–24 lists the bit positions in a 32-bit logic.

Table 8–24. Remote System Upgrade Current State Logic Contents In Status Register

Remote System Upgrade Master State Machine	Status Register Bit	Definition	Description
Factory information (1)	31:30	Master state machine current state	The current state of the remote system upgrade master state machine
	29:24	Reserved bits	Padding bits that are set to all 0's
	23:0	Boot address	The current 24-bit boot address that was used by the configuration scheme as the start address to load the current configuration.
Application information 1 (2)	31:30	Master state machine current state	The current state of the remote system upgrade master state machine
	29	User watchdog timer enable bit	The current state of the user watchdog enable, which is active high
	28:0	User watchdog timer time-out value	The current entire 29-bit watchdog time-out value.
Application information 2 (2)	31:30	Master state machine current state	The current state of the remote system upgrade master state machine
	29:24	Reserved bits	Padding bits that are set to all 0's
	23:0	Boot address	The current 24-bit boot address that was used as the start address to load the current configuration

Notes to Table 8–24:

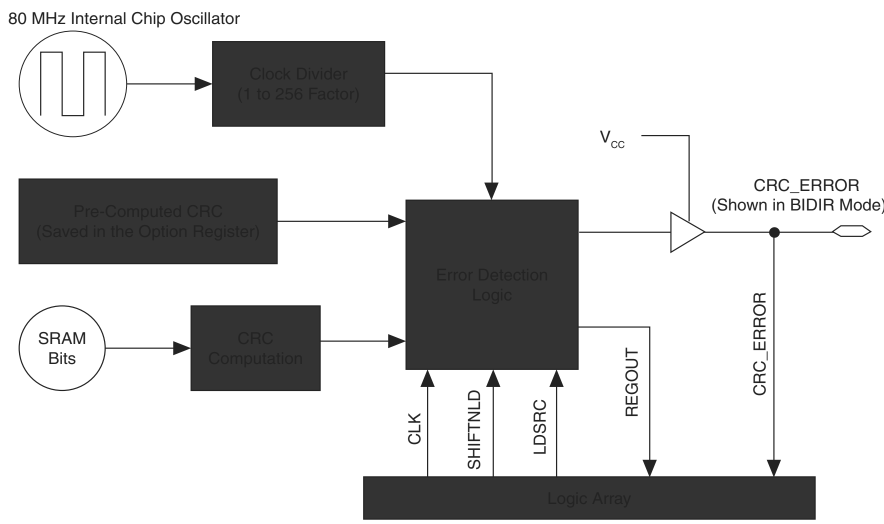
(1) The remote system upgrade master state machine is in factory configuration.

(2) The remote system upgrade master state machine is in application configuration.

The previous two application configurations are available in the previous state registers (previous state register 1 and previous state register 2), but only for debugging purposes.

Figure 9–3 shows the error detection block diagram in FPGA devices and shows the interface that the WYSIWYG atom enables in your design.

Figure 9–3. Error Detection Block Diagram



The user logic is affected by the soft error failure, so reading out the 32-bit CRC signature through the `regout` should not be relied upon to detect a soft error. You should rely on the `CRC_ERROR` output signal itself, because this `CRC_ERROR` output signal cannot be affected by a soft error.

To enable the `cycloneiv_crcblock` WYSIWYG atom, you must name the atom for each Cyclone IV device accordingly.

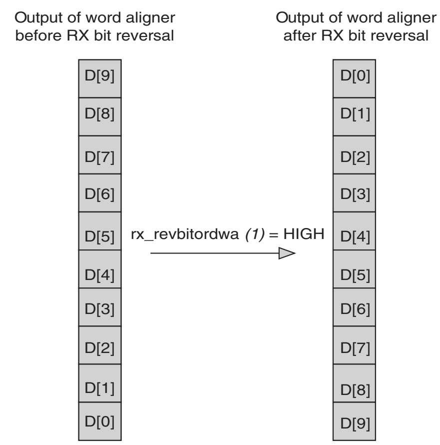
Example 9–1 shows an example of how to define the input and output ports of a WYSIWYG atom in a Cyclone IV device.

Example 9–1. Error Detection Block Diagram

```
cycloneiv_crcblock<crcblock_name>

(

.clk(<clock source>),

.shiftnld(<shiftnld source>),

.ldsrc(<ldsrc source>),

.crcerror(<crcerror out destination>),

.regout(<output destination>),

);
```

synchronization state machine mode. In bit-slip mode, you can dynamically enable the receiver bit reversal using the `rx_revbitorderwa` port. When enabled, the 8-bit or 10-bit data `D[7..0]` or `D[9..0]` at the output of the word aligner is rewired to `D[0..7]` or `D[0..9]` respectively. Figure 1–20 shows the receiver bit reversal feature.

Figure 1–20. Receiver Bit Reversal (1)



Note to Figure 1–20:

(1) The `rx_revbitordwa` port is dynamic and is only available when the word aligner is configured in bit-slip mode.

When using the receiver bit reversal feature to receive MSB-to-LSB transmission, reversal of the word alignment pattern is required.

- Receiver bit-slip indicator—provides the number of bits slipped in the word aligner for synchronization with `rx_bitslipboundaryselectout` signal. For usage details, refer to “Receive Bit-Slip Indication” on page 1–76.

Deskew FIFO

This module is only available when used for the XAUI protocol and is used to align all four channels to meet the maximum skew requirement of 40 UI (12.8 ns) as seen at the receiver of the four lanes. The deskew operation is compliant to the PCS deskew state machine diagram specified in clause 48 of the IEEE P802.3ae specification.

The deskew circuitry consists of a 16-word deep deskew FIFO in each of the four channels, and control logics in the central control unit of the transceiver block that controls the deskew FIFO write and read operations in each channel.

For details about the deskew FIFO operations for channel deskewing, refer to “XAUI Mode” on page 1–67.

Signal Detect at Receiver

In PIPE mode, signal detection is supported with the built-in signal threshold detection circuitry. When electrical idle inference is not enabled, the `rx_signaldetect` signal is inverted and available as `pipeelecidle` port in the PIPE interface.

Lane Synchronization

In PIPE mode, the word aligner is configured in automatic synchronization state machine mode that complies with the PCIe specification. Table 1–16 lists the synchronization state machine parameters that implement the PCIe-compliant synchronization.

Table 1–16. Synchronization State Machine Parameters (1)

Parameter	Value
Number of valid synchronization (/K28.5/) code groups received to achieve synchronization	4
Number of erroneous code groups received to lose synchronization	17
Number of continuous good code groups received to reduce the error count by one	16

Note to Table 1–16:

(1) The word aligner supports 10-bit pattern lengths in PIPE mode.

Clock Rate Compensation

In PIPE mode, the rate match FIFO compensates up to ±300 ppm (600 ppm total) difference between the upstream transmitter and the local receiver reference clock. In PIPE mode, the rate match FIFO operation is compliant to the version 2.0 of the PCIe Base Specification. The PCIe protocol requires the receiver to recognize a skip (`SKP`) ordered set, and inserts or deletes only one `SKP` symbol per `SKP` ordered set received to prevent the rate match FIFO from overflowing or underflowing. The `SKP` ordered set is a /K28.5/ comma (`COM`) symbol followed by one to five consecutive /K28.0/ `SKP` symbols, which are sent by transmitter during the inter-packet gap.

The rate match operation begins after the synchronization state machine in the word aligner indicates synchronization is acquired, as indicated with logic high on `rx_syncstatus` signal. Rate match FIFO insertion and deletion events are communicated to FPGA fabric on the `pipestatus[2..0]` port from each channel.

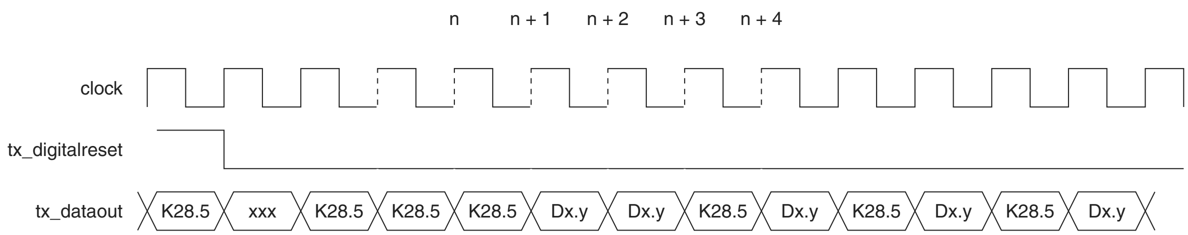
Low-Latency Synchronous PCIe

In PIPE mode, the Cyclone IV GX transceiver supports a lower latency in synchronous PCIe by reducing the latency across the rate match FIFO. In synchronous PCIe, the system uses a common reference clocking that gives a 0 ppm difference between the upstream transmitter's and local receiver's reference clock.

When using common reference clocking, the transceiver supports spread-spectrum clocking. For more information about the SSC support in PCIe Express (PIPE) mode, refer to the *Cyclone IV Device Data Sheet*.

Figure 1–57 shows an example of even numbers of /Dx.y/ between the last automatically sent /K28.5/ and the first user-sent /K28.5/. The first user-sent /K28.5/ code group received at an odd code group boundary in cycle *n* + 3 takes the receiver synchronization state machine in Loss-of-Sync state. The first synchronization ordered-set /K28.5/Dx.y/ in cycles *n* + 3 and *n* + 4 is discounted and three additional ordered sets are required for successful synchronization.

Figure 1–57. Example of Reset Condition in GIGE Mode



Running Disparity Preservation with Idle Ordered Set

During idle ordered sets transmission in GIGE mode, the transmitter ensures a negative running disparity at the end of an idle ordered set. Any /Dx.y/, except for /D21.5/ (part of /C1/ ordered set) or /D2.2/ (part of /C2/ ordered set) following a /K28.5/ is automatically replaced with either of the following:

- A /D5.6/ (/I1/ ordered set) if the running disparity before /K28.5/ is positive
- A /D16.2/ (/I2/ ordered set) if the running disparity before /K28.5/ is negative

Lane Synchronization

In GIGE mode, the word aligner is configured in automatic synchronization state machine mode that complies with the IEEE P802.3ae standard. A synchronization ordered set is a /K28.5/ code group followed by an odd number of valid /Dx.y/ code groups. Table 1–19 lists the synchronization state machine parameters that implements the GbE-compliant synchronization.

Table 1–19. Synchronization State Machine Parameters (1)

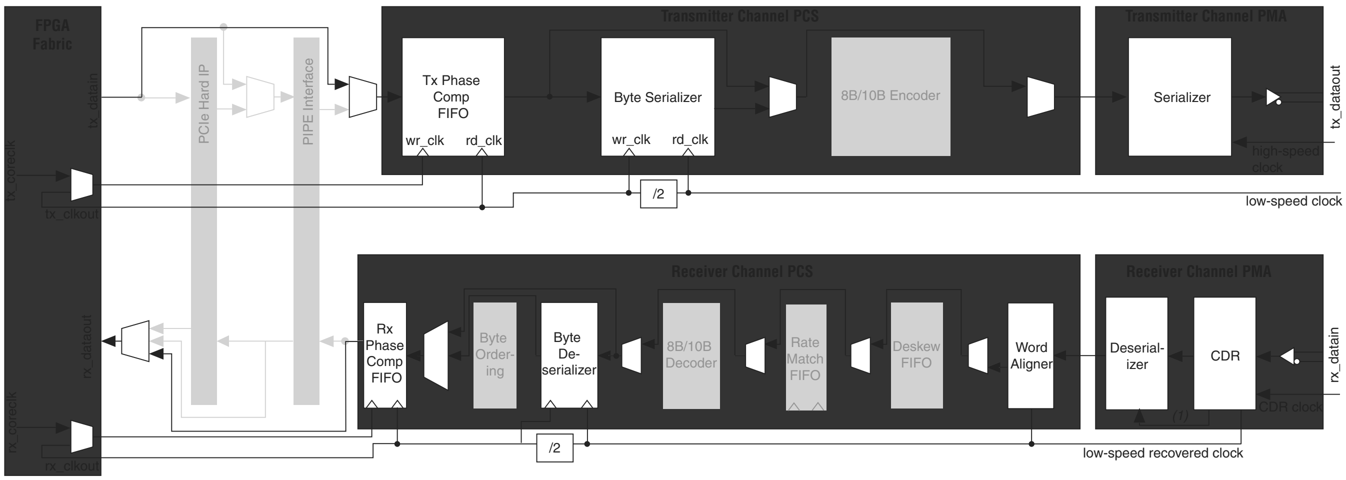
Parameter	Value
Number of valid synchronization ordered sets received to achieve synchronization	3
Number of erroneous code groups received to lose synchronization	4
Number of continuous good code groups received to reduce the error count by one	4

Note to Table 1–19:

(1) The word aligner supports 7-bit and 10-bit pattern lengths in GIGE mode.

Figure 1–68 shows the transceiver channel datapath and clocking when configured in SDI mode.

Figure 1–68. Transceiver Channel Datapath and Clocking when Configured in SDI Mode



Note to Figure 1–68:

(1) High-speed recovered clock.

Cyclone IV E industrial devices I7 are offered with extended operating temperature range.

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Cyclone IV devices. The values are based on experiments conducted with the device and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied at these conditions. Table 1–1 lists the absolute maximum ratings for Cyclone IV devices.

CAUTION

Conditions beyond those listed in Table 1–1 cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time have adverse effects on the device.

Table 1–1. Absolute Maximum Ratings for Cyclone IV Devices *(1)*

Symbol	Parameter	Min	Max	Unit
V_{CCINT}	Core voltage, PCI Express® (PCIe®) hard IP block, and transceiver physical coding sublayer (PCS) power supply	–0.5	1.8	V
V_{CCA}	Phase-locked loop (PLL) analog power supply	–0.5	3.75	V
V_{CCD_PLL}	PLL digital power supply	–0.5	1.8	V
V_{CCIO}	I/O banks power supply	–0.5	3.75	V
V_{CC_CLKIN}	Differential clock input pins power supply	–0.5	4.5	V
V_{CCH_GXB}	Transceiver output buffer power supply	–0.5	3.75	V
V_{CCA_GXB}	Transceiver physical medium attachment (PMA) and auxiliary power supply	–0.5	3.75	V
V_{CCL_GXB}	Transceiver PMA and auxiliary power supply	–0.5	1.8	V
V_I	DC input voltage	–0.5	4.2	V
I_{OUT}	DC output current, per pin	–25	40	mA
T_{STG}	Storage temperature	–65	150	°C
T_J	Operating junction temperature	–40	125	°C

Note to Table 1–1:

(1) Supply voltage specifications apply to voltage readings taken at the device pins with respect to ground, not at the power supply.

Maximum Allowed Overshoot or Undershoot Voltage

During transitions, input signals may overshoot to the voltage shown in Table 1–2 and undershoot to –2.0 V for a magnitude of currents less than 100 mA and for periods shorter than 20 ns. Table 1–2 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage over the lifetime of the device. The maximum allowed overshoot duration is specified as a percentage of high-time over the lifetime of the device.

IOE Programmable Delay

Table 1–40 and Table 1–41 list the IOE programmable delay for Cyclone IV E 1.0 V core voltage devices.

Table 1–40. IOE Programmable Delay on Column Pins for Cyclone IV E 1.0 V Core Voltage Devices (1), (2)

Parameter	Paths Affected	Number of Setting	Min Offset	Max Offset					Unit
				Fast Corner		Slow Corner			
				C8L	I8L	C8L	C9L	I8L	
Input delay from pin to internal cells	Pad to I/O dataout to core	7	0	2.054	1.924	3.387	4.017	3.411	ns
Input delay from pin to input register	Pad to I/O input register	8	0	2.010	1.875	3.341	4.252	3.367	ns
Delay from output register to output pin	I/O output register to pad	2	0	0.641	0.631	1.111	1.377	1.124	ns
Input delay from dual-purpose clock pin to fan-out destinations	Pad to global clock network	12	0	0.971	0.931	1.684	2.298	1.684	ns

Notes to Table 1–40:

(1) The incremental values for the settings are generally linear. For the exact values for each setting, use the latest version of the Quartus II software.

(2) The minimum and maximum offset timing numbers are in reference to setting **0** as available in the Quartus II software.

Table 1–41. IOE Programmable Delay on Row Pins for Cyclone IV E 1.0 V Core Voltage Devices (1), (2)

Parameter	Paths Affected	Number of Setting	Min Offset	Max Offset					Unit
				Fast Corner		Slow Corner			
				C8L	I8L	C8L	C9L	I8L	
Input delay from pin to internal cells	Pad to I/O dataout to core	7	0	2.057	1.921	3.389	4.146	3.412	ns
Input delay from pin to input register	Pad to I/O input register	8	0	2.059	1.919	3.420	4.374	3.441	ns
Delay from output register to output pin	I/O output register to pad	2	0	0.670	0.623	1.160	1.420	1.168	ns
Input delay from dual-purpose clock pin to fan-out destinations	Pad to global clock network	12	0	0.960	0.919	1.656	2.258	1.656	ns

Notes to Table 1–41:

(1) The incremental values for the settings are generally linear. For the exact values for each setting, use the latest version of the Quartus II software.

(2) The minimum and maximum offset timing numbers are in reference to setting **0** as available in the Quartus II software.